T-Global Technology Ltd(Europe and North America)
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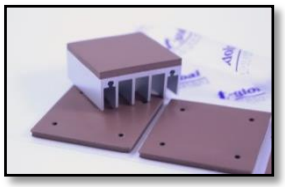
TG Series Thermal Pads

Features： Electrical insulation
Good thermal conductivity
Soft, and high compressibility
Natural tack
Low hardness
Low oil bleed- long term stability

Applications： Electronic components: IC, CPU, MOS
LED, M/B, P/S, Heat Sink,
LCD-TV, Notebook, PC, Telecom Device,
Wireless Hub,.....etc. DDR II Module,
DVD Applications, Hand-set Applications,.....etc.

Specification	Unit	TG2030	TG4040	TG4040LC	TG4040F	TG6050	TGX	Method
Color	-	White	Blue	Blue	Blue	Red	Gray	Visual
Thickness	mm	0.5~5.0	0.5~5.0	0.3~5.0	0.5~5.0	0.5~5.0	0.5~2.0	ASTM D374
Thermal Conductivity	W / mK	2	4	3.5	4	6	12	ASTM D5470
Flame Rating	-	V-0	V-0	V-0	V-0	V-0	V-0	UL 94
Breakdown Voltage	KV / mm	16	15	4	15	13	12	ASTM D149
Weight Loss	%	<1	<1	<0.4	<1	<1	<1	ASTM E595
Specific Gravity	g / cm^3	2.4	2.8	2.6	2.8	3.2	3.4	ASTM D792
Working Temperature	℃	-45~+200	-45~+200	-45~+200	-45~+200	-45~+200	-45~+200	-
Volume Resistance	Ohm-cm	$>10^{12}$	$>10^{12}$	$>10^{11}$	$>10^{12}$	$>10^{12}$	$>10^{11}$	ASTM D257
Elongation	%	300	100	100	100	50	-	ASTM D412
Tensile Strength	Kgf / cm^2	1	1	60	1	0.5	-	ASTM D412
Standard Shape	Sheet ones							Sheet ones
Hardness	Shore 00	30	35	40	35	60	65	ASTM D2240

H48 Series Thermal Pads



Features： Great thermal conductivity
Soft, and high compressibility
Easy to assemble
Natural tack
Electrical insulation

Applications： Electronic components: IC, CPU, MOS
LED, M/B, P/S, Heat Sink,
LCD-TV, Notebook, PC, Telecom Device,
Wireless Hub,.....etc. DDR II Module,
DVD Applications, Hand-set Applications,.....etc.

Specification	Unit	H48-2	H48-2K	H48-6	H48-6A	H48-6G	H48-6S	Method
Color	-	Dark Red	Dark Red	Dark Gray	Henna	Gray	Dark Red	Visual
Thickness	mm	0.3~20	0.1/0.2/0.3	0.3~20	0.3~20	0.3~5.0	0.23	ASTM D374
Thermal Conductivity	W / mK	2.2	2.2	3.2	4	6	1.8	ASTM D5470
Flame Rating	-	V-0	V-0	V-0	V-0	V-0	V-0	UL 94
Breakdown Voltage	KV / mm	5	1.2/2.5/3.5	2	2	13	7	ASTM D149
Weight Loss	%	<1	<0.5	<1	<1	<1	<1	ASTM E595
Specific Gravity	g / cm^3	2.43	2.4	2.42	2.48	3.09	1.95	ASTM D792
Working Temperature	℃	-40~+200	-45~+200	-40~+200	-40~+200	-40~+200	-40~+200	-
Volume Resistance	Ohm-cm	$>10^{11}$	$>10^{11}$	$>10^{11}$	$>10^{11}$	$>10^{12}$	$>10^{12}$	ASTM D257
Elongation	%	282	50	130	120	60	0.2	ASTM D412
Tensile Strength	Kgf / cm^2	7	-	8	8	6	66.5	ASTM D412
Standard Shape	Sheet ones							Sheet ones
Hardness	Shore A	25	85	30	25	35	90	ASTM D2240

L37 Series Thermal Pads

Features： Great thermal conductivity
Soft, and high compressibility
Easy to assemble
Natural tack
Electrical insulation

Applications： Electronic components: IC, CPU, MOS
LED, M/B, P/S, Heat Sink,
LCD-TV, Notebook, PC, Telecom Device,
Wireless Hub,.....etc. DDR II Module,
DVD Applications, Hand-set Applications,.....etc.

Specification	Unit	L37-3	L37-3F	L37-3S	L37-3L	L37-5	L37-5S	Method
Color	-	Yellow	Yellow	Yellow	Yellow	Gray	Gray	Visual
Thickness	mm	0.3~20	0.25/0.3/0.45	0.3~20	0.5~10	0.3~20	0.5~5.0	ASTM D374
Thermal Conductivity	W / mK	1.7	1.4	1.95	1.5	1.6	1.8	ASTM D5470
Flame Rating	-	V-0	V-0	V-0	V-0	V-0	V-0	UL 94
Breakdown Voltage	KV / mm	>10	3/4/5	>13	15	>10	16	ASTM D149
Weight Loss	%	<1	<1	<1	<0.2	<1	<1	ASTM E595
Specific Gravity	g / cm^3	2.17	2	2.21	2.4	2.38	2.4	ASTM D792
Working Temperature	℃	-40~+200	-40~+200	-40~+200	-45~+200	-40~+200	-45~+200	-
Volume Resistance	Ohm-cm	$>10^{12}$	$>10^{13}$	$>10^{12}$	$>10^{11}$	$>10^{12}$	$>10^{12}$	ASTM D257
Elongation	%	-	5	350	20	300	300	ASTM D412
Tensile Strength	Kgf / cm^2	66.4	150	8	-	12	1	ASTM D412
Standard Shape	Sheet ones							Sheet ones
Hardness	Shore	Shore 00 55	Shore A 90	Shore 00 55	Shore A 15	Shore A 25	Shore 00 25	ASTM D2240

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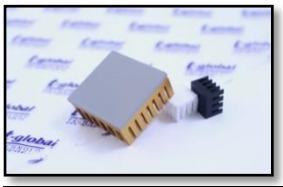
Li Series Thermal Tapes

Features： Good adhesion
High thermal conductivity
Soft and compressibility
Easy to assemble

Applications： Electronic components: IC, CPU, MOS
LED, M/B, P/S, Heat Sink,
LCD-TV, Notebook, PC, Telecom Device,
Wireless Hub,……etc. DDR II Module,
DVD Applications, Hand-set Applications,……etc.

Specification	Unit	Li98	Li98C	Li98CN	Li98P	Liv2	Li2000	Li2000A	Method
Color	-	White	White	White	White	White	White	White	Visual
Thickness	mm	0.15/0.25		0.18	0.125/0.14	0.15/0.25	0.15/0.25	0.2	ASTM D374
Reinforcement Carrier	-	Fiberglass		-	Polyimide	玻纖 Fiberglass		-	-
Thermal Conductivity	W/m.K	0.95	1.8	2	1.7	1.0	1.2	2	ASTM D5470
Density	g/cm^3	1.85	1.8	1.8	1.3/1.2	1.85	1.6	2.3	ASTM D792
Breakdown Voltage (Vac)	kV	2/3	2/3	5	4/5	2/3	2/3	>3.5	ASTM D149
Breakdown Voltage (Vdc)	kV	3/4	3/4	6	5/6	3/4	3/4	>4.5	ASTM D149
Working Temperature	°C	-30~120			-30~120	-30~120	-45~170	-45~170	-
Short Time Use Temp. (30sec)	°C	200			250	180	288	260	-
Thermal Impedance @10psi	°Cin^2/W	0.96/1.3	0.66/0.92	0.75	0.8/0.9	0.78/1.3	0.70/1.17	0.71	ASTM D5470
Thermal Impedance @50psi	°Cin^2/W	0.63/1.1	0.55/0.9	0.68	0.75/0.81	0.65/1.1	0.63/1.07	0.51	ASTM D5470
Initial Tack	cm	10/8	14/2	15	15	11/10	10	>30	PSTC-6
Lap Shear Strength	N/cm^2	61	55/50	55	63/62	60	74/76	35	ASTM D1002
Tensile Strength	psi	200/400	200/400	-	500/600	200/400	450/650	-	ASTM D412
Die Shear Strength @25°C	N/cm^2	120	109/100	100	115	120	113/126	60	-
Die Shear Strength @80°C	N/cm^2	69	68	55	66/64	69	80/85	50	-
Holding Power 1000g@25°C using 1 in^2	min	>10000					>40000		PSTC-7
Holding Power 1000g@80°C using 1 in^2	min	>10000					>40000		PSTC-7
90° Peeling Strength (Aluminum)	N/inch	>10/>12	>6/>8	>8	>10	>15/>16	-	-	ASTM D3330

PC Series Non-Silicone Thermal Pads



Features： Low contact thermal impedance
Good thermal conductivity
Silicone free
Long term stability

Applications： Electronic components: IC, CPU, MOS
LED, M/B, P/S, Heat Sink,
LCD-TV, Notebook, PC, Telecom Device,
Wireless Hub,……etc. DDR II Module,
DVD Applications, Hand-set Applications,……etc.

Specification	Unit	PC93	PC94	Method
Color	-	Gray	Red	Visual
Thickness	mm	0. 5~5.0	0.5~5.0	ASTM D374
Thermal Conductivity	W / mK	2	4	ASTM D5470
Flame Rating	-	V-0	V-0	UL94
Breakdown Voltage	KV / mm	10	10	ASTM D149
Weight Loss	%	<1	<1	ASTM E595
Specific Gravity	g / cm^3	2.1	2.5	ASTM D792
Working Temperature	°C	-30~125	-30~125	-
Volume Resistance	Ohm-cm	>10^{12}	10^{10}	ASTM D257
Elongation	%	350	100	ASTM D412
Tensile Strength	Kgf / cm^2	1	2	ASTM D412
Standard Shape	Sheet ones			Sheet ones
Hardness	Shore 00	65	60	ASTM D2240

Thermal Gel

Features： High thermal conductivity
Long term stability

Applications： Electronic components: IC, CPU, MOS
LED, M/B, P/S, Heat Sink,
LCD-TV, Notebook, PC, Telecom Device,
Wireless Hub,……etc. DDR II Module,
DVD Applications, Hand-set Applications,……etc.

Specification	Unit	A96AB	S720AB	S730	Method
Color	-	White/Black	White	Gray	Visual
Thermal Conductivity	W / mK	2.5	0.8	2.0	ASTM D5470
Breakdown Voltage	KV	10	6	>12	ASTM D149
Weight Loss	%	<1	<1	-	ASTM E595
Specific Gravity	g / cm^3	1.8	1.97	2.5	ASTM D792
Working Temperature	°C	-25~150	-40~180	-50~200	-
Viscosity	Cps	1800~2500	2000~3000	<50000	ASTM D2393
Standard Package	Pot/Tube	1KG	1KG	100g/1KG	-
Hardness	Shore A	80	40~50	20	ASTM D2240

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GT Series Thermal Pads

Features： Smooth surface & low contact resistance
Great thermal performance at low pressure
Usable over wide range of temp.
Electrical insulation
Complies with UL standards

Applications： Electronic components: IC, CPU, MOS
LED, M/B, P/S, Heat Sink,
LCD-TV, Notebook, PC, Telecom Device,
Wireless Hub,.....etc. DDR II Module,
DVD Applications, Hand-set Applications,.....etc.

Specification	Unit	GT15	GT20	GT30	Method
Color	-	Yellow	Green	Pink	Visual
Thickness	mm	0.23	0.3	0.35	-
Thermal Conductivity	W / mK	1.5	2.0	3.0	ASTM D5470
Flame Rating	-	V-0	V-0	V-0	UL 94
Breakdown Voltage	KV / mm	4	4	3	ASTM D149
Weight Loss	%	<0.2	<0.2	<0.2	ASTM E595
Specific Gravity	g / cm^3	2.3	2.6	2.8	ASTM D792
Working Temperature	℃	-45~180	-45~180	-45~180	-
Volume Resistance	Ohm-cm	>10^{11}	>10^{11}	>10^{11}	ASTM D257
Elongation	%	60	60	30	ASTM D412
Tensile Strength	Kgf / cm^2	200	200	100	ASTM D412
Standard Shape	Sheet ones				Sheet ones
Hardness	Shore A	90	85	85	ASTM D2240

Thermal Putty

Features： High thermal conductivity
Compressibility
Low thermal resistance
Great for North Bridge IC

Applications： Electronic components: IC, CPU, MOS
LED, M/B, P/S, Heat Sink,
LCD-TV, Notebook, PC, Telecom Device,
Wireless Hub,.....etc. DDR II Module,
DVD Applications, Hand-set Applications,.....etc.

Specification	Unit	TG-NSP25	TG4040 PUTTY	Method
Material	-	Silicone-free	Silicone-type	-
Color	-	Gray	Blue	Visual
Solid Content	%	100(one-part)	100(one-part)	-
Thermal Conductivity	W / mK	2.5	3.0	ASTM D5470
Viscosity 0.5rpm	Pa·s	5,000	3,000	Brookfield
Density	g / cm^3	2.6	3.0	ASTM D792
Low MW Siloxane(D4-10)	ppm	0	50	GC/MS
TML	%	0.2	0.3	ASTM E595
CVCM	%	0.1	0.09	ASTM E595
Volume Resistivity	Ohm-cm	10^{14}	10^{14}	ASTM D257
Working Temperature	℃	-50~150	-50~180	-
Standard Package	Pot/Tube	78g/143g/1KG	90g/165g/1KG	-

CP Series Thermal Cap

Features： Low thermal contact resistance
Electrical insulation

Standard sizes (mm)：
1. CP22 TO-220: 11.4x16x5.8
2. CP23 TO-220: 11.4x21.5x5.8
3. CP33 TO-247: 17.5x28.5x5.8

Applications： Electronic components: IC, CPU, MOS
LED, M/B, P/S, Heat Sink,
LCD-TV, Notebook, PC, Telecom Device,
Wireless Hub,.....etc. DDR II Module,
DVD Applications, Hand-set Applications,.....etc.

Specification	Unit	CP22/CP23/CP33	Method
Material	-	Silicone	-
Color	-	Gray	Visual
Thickness	mm	0.3 / 0.45	-
Thermal Conductivity	W / mK	1.9	ASTM D5470
Breaking Voltage (Vac)	KV	4 / 6	ASTM D149
Breaking Voltage (Vdc)	KV	6 / 8	ASTM D149
Dielectric Constant	1000Hz	5.8	ASTM D150
Flame Rating	-	V-0	UL94
Density	g / cm^3	2.55	ASTM D792
Working Temperature	℃	-45~180	-
TML	%	<0.2	ASTM E595
Hardness	Shore A	75	ASTM E595

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Ti900 Thermal Insulators

Features : Electrical insulation
Low thermal impedance
Easy to assemble

Applications : Electronic components: IC, CPU, MOS, LED, M/B, P/S, Heat Sink, LCD-TV, NB, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set Applications, ... etc.

Specification	Unit	Ti900	Method
Color	-	Gray	Visual
Thickness	mm	0.12	-
Base	-	Polyimide	ASTM D5470
Thermal Conductivity	W / mK	1.8	ASTM D374
ThermalResistance@10psi	K in^2 / W	0.852	ASTM D5470
ThermalResistance@30psi	K in^2 / W	0.508	ASTM D5470
ThermalResistance@50psi	K in^2 / W	0.402	ASTM D5470
Breaking Voltage (Vac)	KV	6	ASTM D149
Volume Resistance	Ohm-cm	$>10^{12}$	ASTM D257
Working Temperature	℃	-50~180	-
Tensile Strength	psi	5000	ASTM D412
Elongation	%	40	ASTM D412
Flame Rating	-	V-0	UL94

XL-25 Ceramic Heat Spreaders

Features : Large contact area
Low weight
High voltage breakdown
High resistance
Easy to assemble
Good heat transferring

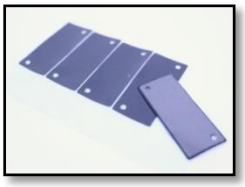
Applications : Electronic components: IC, CPU, MOS, LED, M/B, P/S, Heat Sink, LCD-TV, NB, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set Applications, ... etc.

Size (mm)

1. 10x10x2.0 (Flat)
2. 15x15x2.0 (Flat)
3. 15x15x2.5 (Flat)
4. 20x15x2.0 (Flat)
5. 20x20x2.0 (Flat)
6. 20x20x2.5 (Flat)
7. 38x38x11.5 (Fin)
8. 30x30x2.0 (Flat)
9. 30x30x2.5 (Flat)
10. 40x40x2.0 (Flat)
11. 40x40x2.5 (Flat)
12. 40x40x3.0 (Dots)
13. 25x25x5.0 (Fin)
14. 50x50x3.0 (Dots)

Specification	Unit	XL-25	Method
Color	-	Green/Gray	Visual
Thermal Conductivity	W / mK	6.79	-
Breaking Voltage	V	500	ASTM D149
Specific Gravity	g / cm^3	1.89	CNS 619
Surface Resistance	Ohm	$>10^9$	ASTM D257
Flexural Strength	Kgf /cm^2	47.5	CNS 12701
Porosity	%	30	CNS 619
Working Temperature	℃	<500	-
Linear Temperature Expansion Coefficient	10^{-6}	4.13	RT~300℃
Main Composition	-	$SiC/Al_2O_3/SiO_2$	-
Hardness	Moh's	5~6	DIN En101-1992

T68 Artificial Graphite Sheets



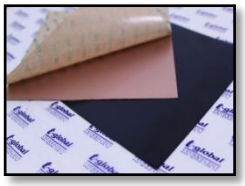
Features : Great thermal conductivity: 1500W/m.K
Electrical insulation
Ultra thin; low mass
Environmental friendly
Low contact resistance

Applications : Electronic components: IC, CPU, MOS, LED, M/B, P/S, Heat Sink, LCD-TV, NB, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set Applications, ... etc.

Specification		Unit	T68	Method
Thickness		μm	25	Micrometer
Thermal Conductivity	XY axis	W / mK	1500	AC calorimeter
	Z axis	W / mK	5	Laser Flash
Thermal Diffusivity		cm^2 / S	8.5	AC calorimeter
Density		g / cm^3	2.1	Archimedes law
Electrical Conductivity		S / cm	13000	JIS K7194
Curvature		-	Flexible	MIT
Heat Resistance		℃	400	AC calorimeter
Heat Capacity (SHC)		J / g-K	0.895	-

PH3 Heat Spreaders

Features : Large temp. reduction
Long term stability
Easy to assemble



Applications : Electronic components: IC, CPU, MOS, LED, M/B, P/S, Heat Sink, LCD-TV, NB, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set Applications, ... etc.

Specification	Unit	PH3
Color	-	Black
Thickness	mm	0.06/0.11/0.21
Insulator	-	Polyester
Thermal Conductor	-	Copper
Pressure-sensitive Adhesive	-	Acrylic PSA
Metal Layer Thermal Conductivity	W/m.K	400
Coating Layer Thermal Conductivity	W/m.K	1.2
Volume Resistance	Ωcm	10^{12}
Working Temperature	°C	-30~120
Initial Tack	cm	18/15/11
30° Peeling Strength (Aluminum)	N/in	8/10/12
Breaking Voltage(AC)	KV	2/2/3